KSM9N25C/KSMF9N25C

KERSEMI ELECTROIC CO.,LTD.

250V N-Channel MOSFET

TO-220

TO-220F

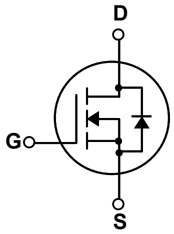
Features

- 8.8A, 250V, $R_{DS(on)}$ = 0.43Ω @V_{GS} = 10 V
- Low gate charge (typical 26.5 nC)
- Low Crss (typical 45.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

General Description

These N-Channel enhancement mode power field effect transistors are produced using Kersemi proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supplies and motor controls.



Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter	KSM9N25C	KSMF9N25C	Units
V_{DSS}	Drain-Source Voltage	250		V
I_D	Drain Current - Continuous (T_C = 25°C)	8.8	8.8 *	A
	- Continuous (T_C = 100°C)	5.6	5.6 *	A
I_{DM}	Drain Current - Pulsed (Note 1)	35.2	35.2 *	A
V_{GSS}	Gate-Source Voltage	± 30		V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	285		mJ
I_{AR}	Avalanche Current (Note 1)	8.8		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	7.4		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5		V/ns
P_D	Power Dissipation (T_C = 25°C)	74	38	W
	- Derate above 25°C	0.59	0.3	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		°C
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		°C

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	KSM9N25C	KSMF9N25C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.69	3.29	°C/W
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Electrical Characteristics

T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 μA	250	--	--	V
ΔBV_{DSS} / ΔT_J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	--	0.30	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 250 V, V_{GS} = 0 V	--	--	10	μA
		V_{DS} = 200 V, T_C = 125°C	--	--	100	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30 V, V_{DS} = 0 V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30 V, V_{DS} = 0 V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 μA	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 4.4 A	--	0.35	0.43	Ω
g_{FS}	Forward Transconductance	V_{DS} = 40 V, I_D = 4.4 A (Note 4)	--	7.0	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	--	545	710	pF
C_{oss}	Output Capacitance		--	115	150	pF
C_{rss}	Reverse Transfer Capacitance		--	45.5	60	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 125 V, I_D = 8.8 A, R_G = 25 Ω (Note 4, 5)	--	15	40	ns
t_r	Turn-On Rise Time		--	85	180	ns
$t_{d(off)}$	Turn-Off Delay Time		--	90	190	ns
t_f	Turn-Off Fall Time		--	65	140	ns
Q_g	Total Gate Charge	V_{DS} = 200 V, I_D = 8.8 A, V_{GS} = 10 V (Note 4, 5)	--	26.5	35	nC
Q_{gs}	Gate-Source Charge		--	3.5	--	nC
Q_{gd}	Gate-Drain Charge		--	13.5	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	8.8	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	35.2	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 8.8 A	--	--	1.5	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0 V, I_S = 8.8 A, dI_F / dt = 100 A/μs (Note 4)	--	218	--	ns
Q_{rr}	Reverse Recovery Charge		--	1.58	--	μC

Notes:
1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 5.9mH, I_{AS} = 8.8A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
3. $I_{SD} \leq 8.8A$, di/dt ≤ 300A/μs, $V_{DD} \leq BV_{DSS}$, Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Characteristics

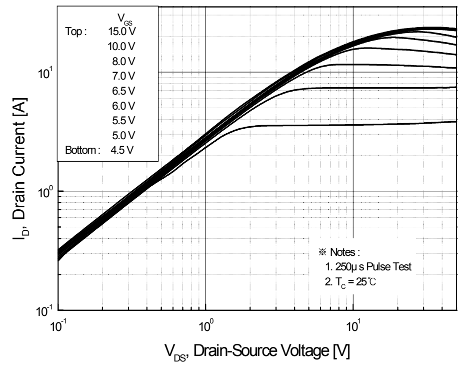


Figure 1. On-Region Characteristics

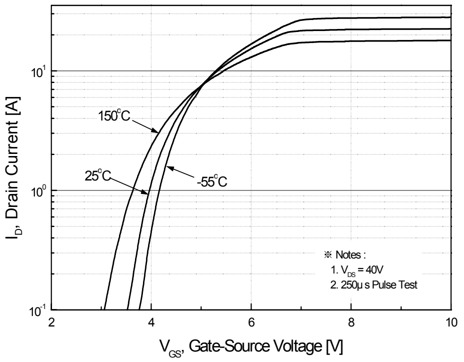


Figure 2. Transfer Characteristics

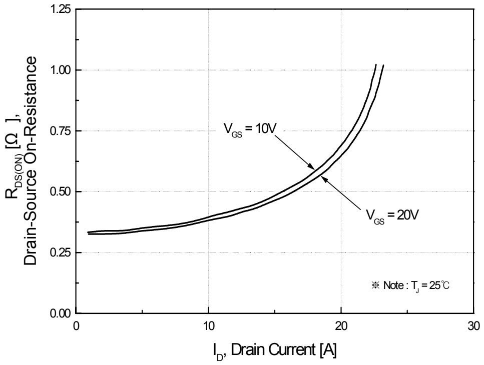


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

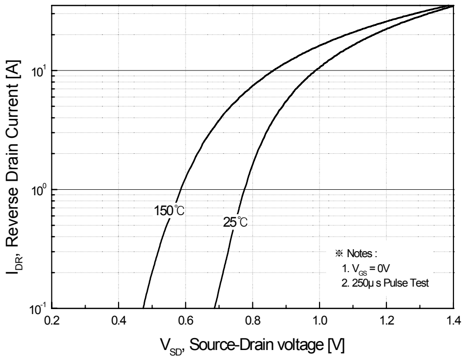


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

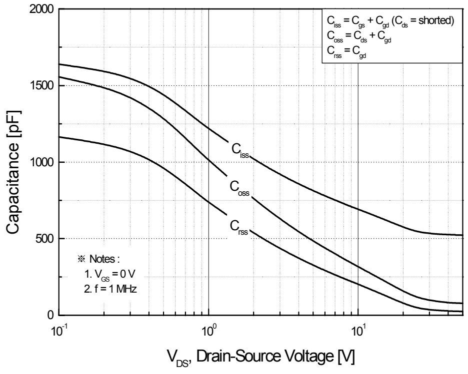


Figure 5. Capacitance Characteristics

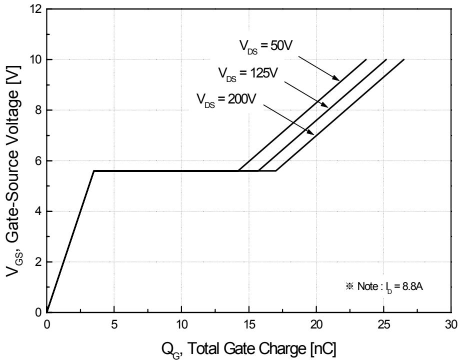


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

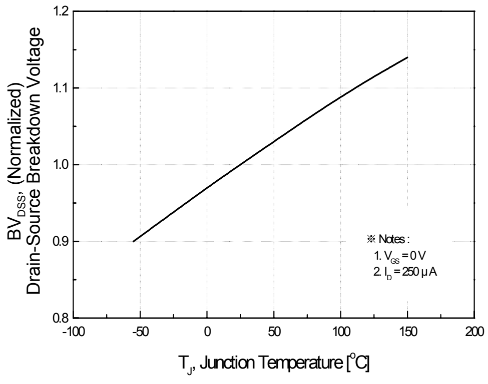


Figure 7. Breakdown Voltage Variation vs Temperature

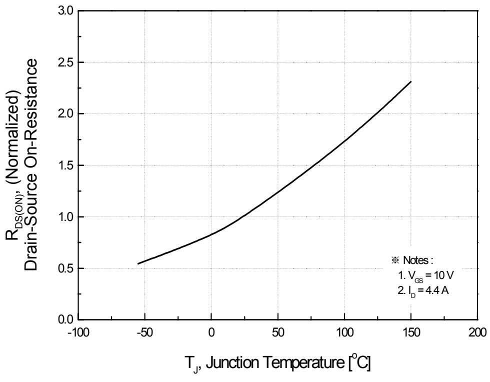


Figure 8. On-Resistance Variation vs Temperature

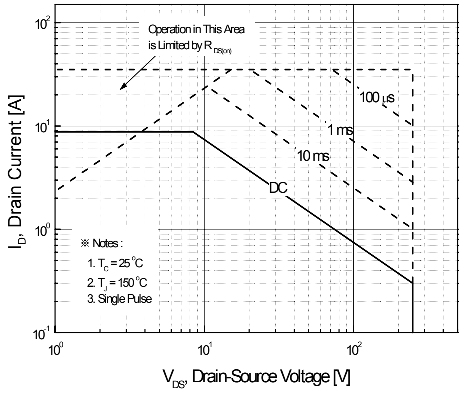


Figure 9-1. Maximum Safe Operating Area for FQP9N25C

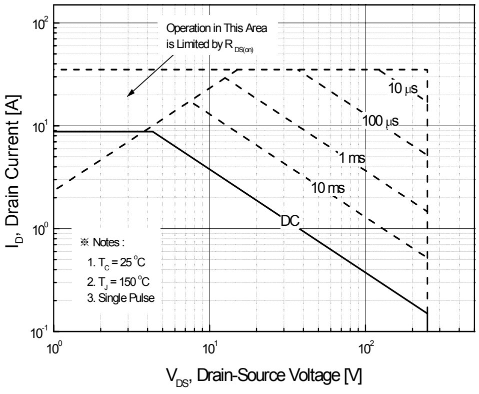


Figure 9-2. Maximum Safe Operating Area for FQPF9N25C

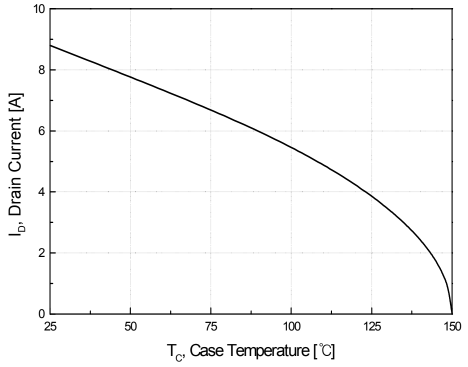


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

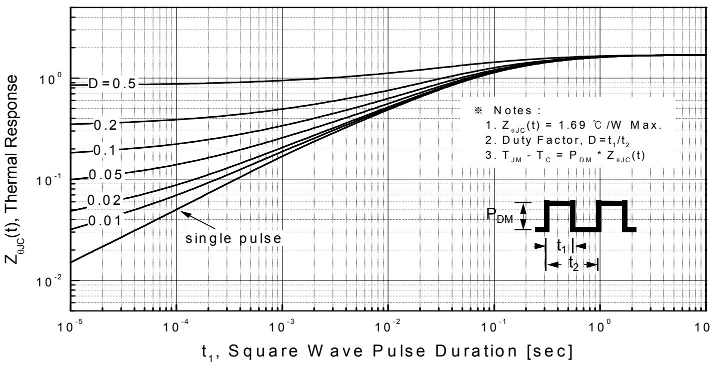


Figure 11-1. Transient Thermal Response Curve for FQP9N25C

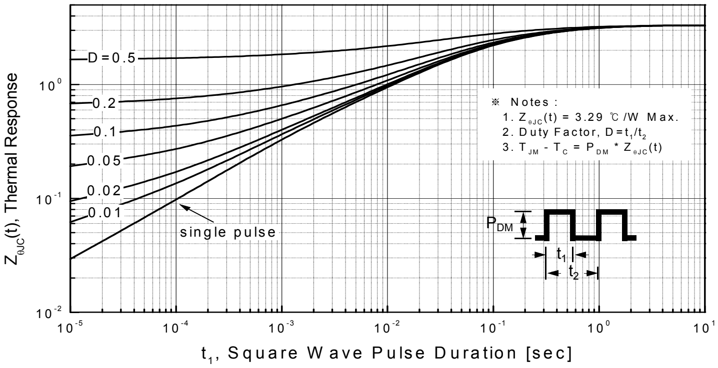
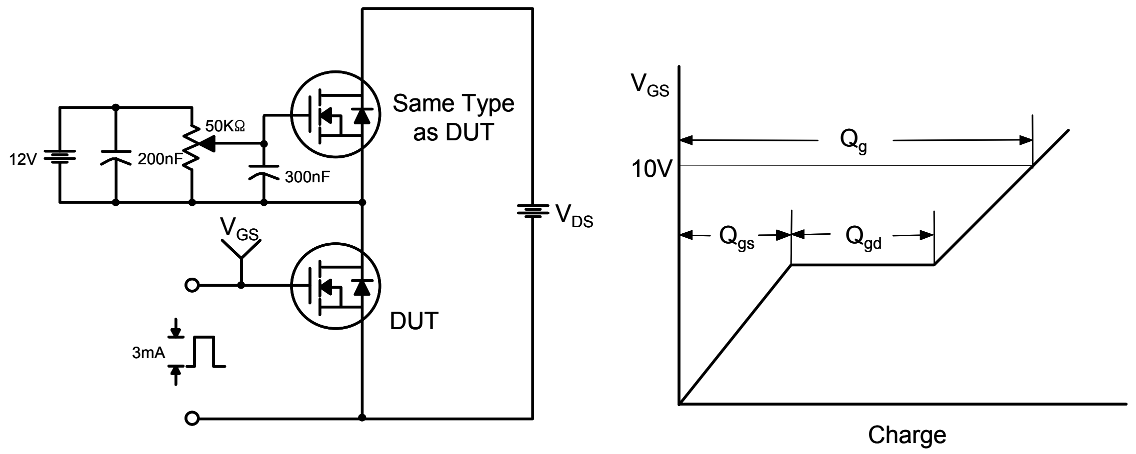
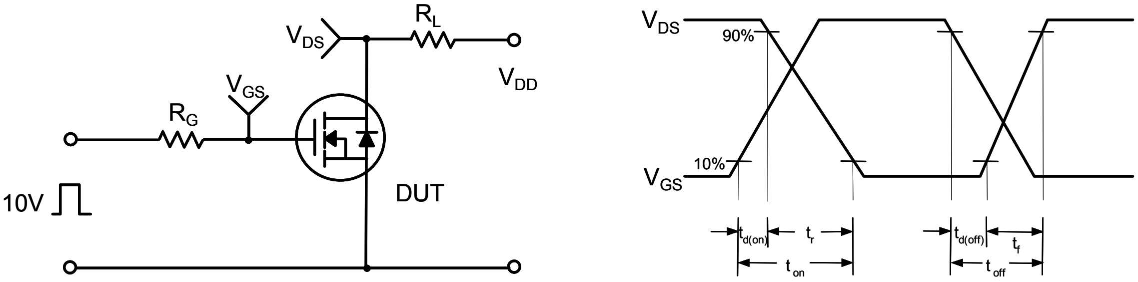


Figure 11-2. Transient Thermal Response Curve for FQPF9N25C

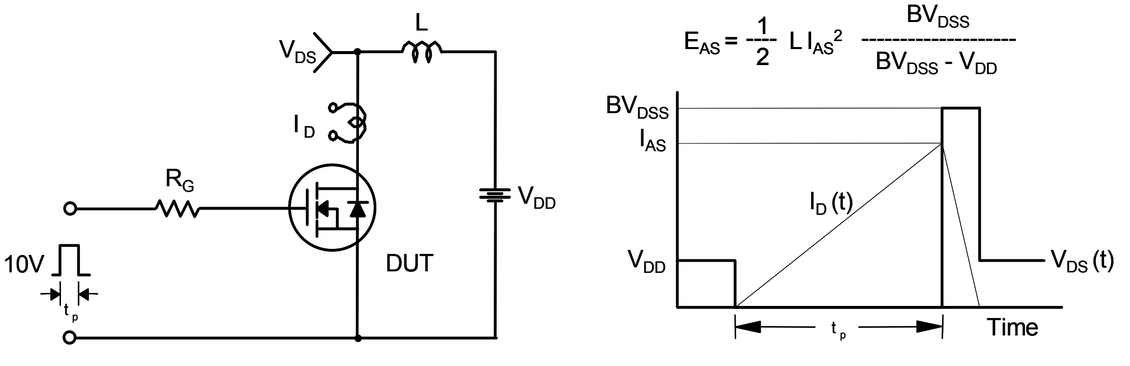
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms